

October 15, 2003

To: Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/623,910 07/18/03

S.L. Shue, M.H. Tsai

METHOD FOR INTEGRATING LOW-K MATERIALS IN SEMICONDUCTOR FABRICATION

Grp. Art Unit:

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56. Copies of each document is included herewith.

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 20, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

10/20/0

TSMC-99-132CC

U.S. Patent 5,827,776 to Bandyopadhyay et al., "Method of Making an Integrated Circuit which Uses an Etch Stop for Producing Staggered Interconnect Lines", discloses a multilevel interconnect structure using staggered interconnects to reduce electric field coupling between interconnect lines.

- U.S. Patent 5,602,423 to Jain, "Damascene Conductors with Embedded Pillars", discloses damascene conductors with embedded pillars to prevent erosion during chemical-mechanical polishing.
- U.S. Patent 5,110,712 to Kessler et al., "Incorporation of Dielectric Layers in a Semiconductor", discloses a metal interconnect in a polymer, low-K dielectric layer.
- U.S. Patent 5,744,394 to Iguchi et al., "Method for Fabricating a Semiconductor Device Having Copper Layer", discloses a dual damascene process for forming interconnections.

Sincerely,

Stephen B. Ackerman,

Reg. No. 37761

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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include conv of this form with next communication to the applicant